



**LTM8003-3.3 9mmX6.25mmX3.42mm (TABLE OF MATERIAL DECLARATION)**

*This product is RoHS compliant per EU RoHS Directive 2003/95/EC.*

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+),  
polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	HL832NSF-LCA, AUS308	0.0360	Cured thermosetting resin (including inorganic filler)	Trade secret	0.00721	20.04
				Continuous Filament Fiber Glass	65997-17-3	0.00512	14.23
				Copper	7440-50-8	0.01850	51.39
				Modified Epoxy Acrylate Resin	186511-06-8	0.00204	5.67
				C.I pigment blue 15	147-14-8	0.00002	0.06
				Silicon dioxide	7631-86-9	0.00106	2.94
				Barium Sulfate	7727-43-7	0.00001	0.02
				3-methoxy-3-methylbutylacetate	103429-90-9	0.00033	0.93
				Organic yellow pigment	Trade secret	0.00002	0.06
				Dipropylene glycol monomethyl ether	34590-94-8	0.00018	0.51
				Heavy Aromatic Solvent naphtha	64742-94-5	0.00062	1.71
2	Solder Ball	SAC305	0.0422	Talc	14807-96-6	0.00088	2.44
				Tin	7440-31-5	0.04074	96.50
				Silver	7440-22-4	0.00127	3.00
				Copper	7440-50-8	0.00021	0.50
3	Die	Silicon	0.0022	Silicon	7440-21-3	0.00217	100.00
4	Component	Component	0.1375	Component	-	0.13750	100.00
5	Solder paste	95Sn5Sb	0.0033	Tin	7440-31-5	0.00315	95.00
				Antimony	7440-36-0	0.00017	5.00
6	Encapsulation	EpoxyResin	0.2922	Solid Epoxy Resin	Trade secret	0.00877	3.00
				Phenol Resin	Trade secret	0.00877	3.00
				Fused Silica	60676-86-0	0.26441	90.50
				Carbon Black	1333-86-4	0.00146	0.50
				Metal Hydroxide	Trade secret	0.00877	3.00
Total Package Weight			0.5134				

Note: Composition derived from MSDS and material C of C from Vendors  
Component Weight based on assembly of generic parts